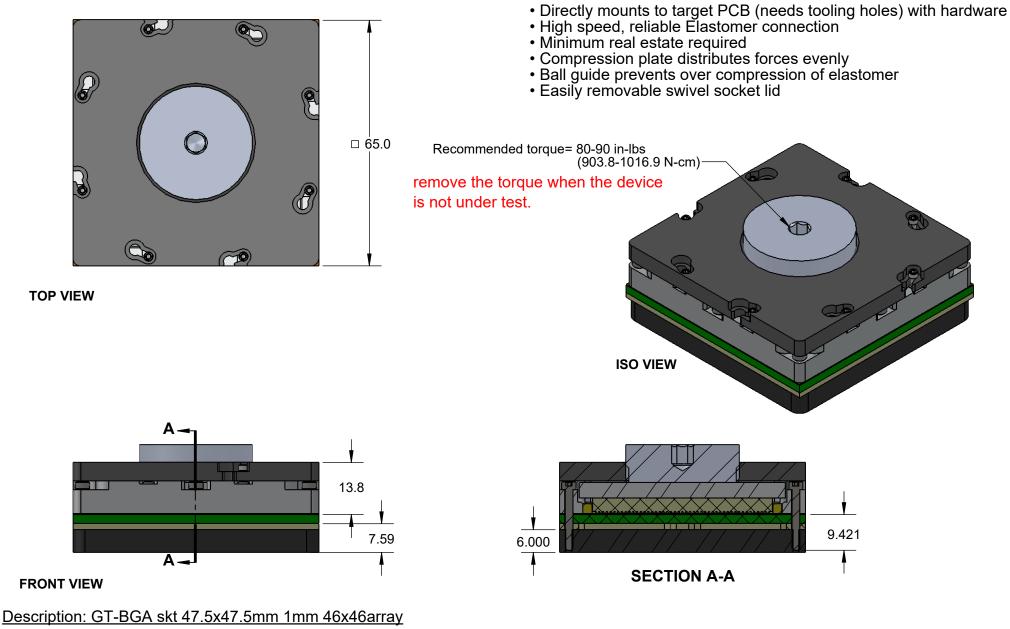
GT-BGA DIRECT MOUNT, SOLDERLESS SOCKET Features



Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

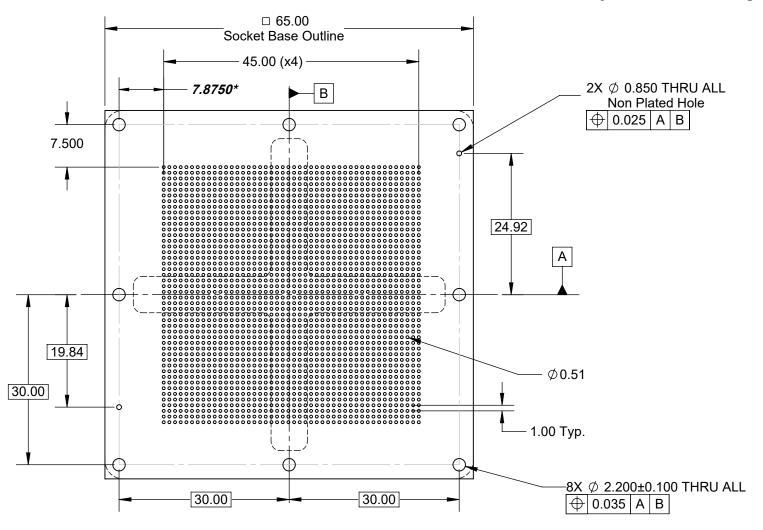
<u>Tolerances:</u> Hole diameters ± 0.03 mm [$\pm 0.001^{"}$], Pitches (from true position) ± 0.025 mm [$\pm 0.001^{"}$], substrate thickness tolerance $\pm 10\%$, all other tolerances ± 0.13 mm [$\pm 0.005^{"}$] unless stated otherwise. Materials and specifications are subject to change without notice.



awing	Material: N/A
onics, Inc. 4-0204 tronics.com	Finish: N/A Weight: 240.49

STATUS: Released	SHEET: 1 OF 4	REV. A
ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 1:1
FILE: GT-BGA-2050 Dwg	DATE: 05/19/2016	

*Note: BGA pattern is not symmetrical with respect to the mounting holes. It is shifted by 0.375mm to the right of center.

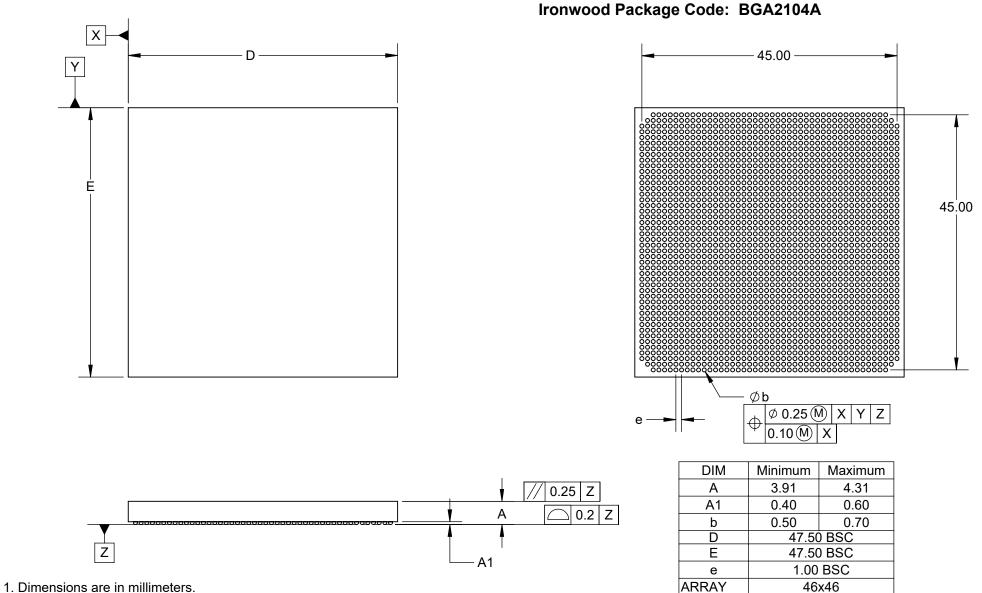


Description: Recommended PCB Layout

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. <u>Tolerances:</u> Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

Target PCB Recommendations
Total thickness: 2mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

	GT-BGA-2050 Drawing		STATUS: Released	SHEET: 2 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204	Finish: N/A Weight: 240.49	ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 3:2	
7	www.ironwoodelectronics.com		FILE: GT-BGA-2050 Dwg	DATE: 05/19/2016	



- Interpret dimensions and tolerances per ASME Y14.5M-1994.
 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 Parallelism measurement shall exclude any effect of mark on top surface of package.

Description: Compatible BGA

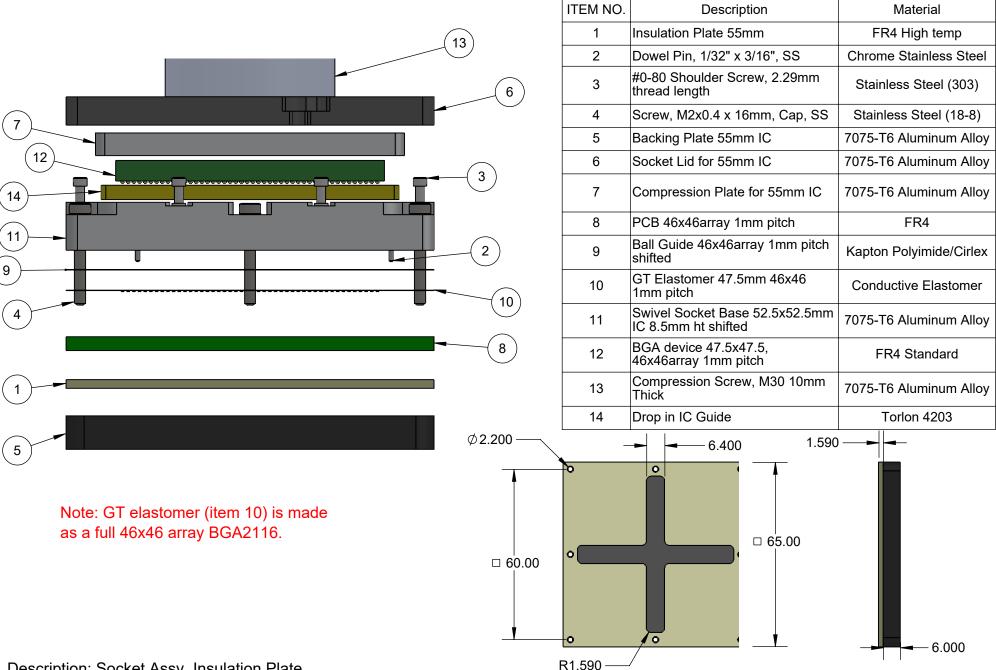
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

G	T-BGA-2050 Drawing	Material: N/A	STATUS: Released	SHEET: 3 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Finish: N/A Weight: 240.49	ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 3:2	
			FILE: GT-BGA-2050 Dwg	DATE: 05/19/2016	

PIN COUNT

2104



Description: Socket Assy, Insulation Plate

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance	£10%, all
other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.	

	GT-BGA-2050 Drawing	Finish: N/A Weight: 240.49	STATUS: Released	SHEET: 4 OF 4	REV. A
FB	Ironwood Electronics, Inc. Tele: (800) 404-0204		ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 3:2
	www.ironwoodelectronics.com		FILE: GT-BGA-2050 Dwg	DATE: 05/19/2016	

BACKING AND INSULATION PLATE